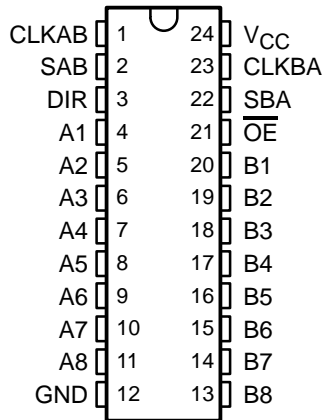


SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

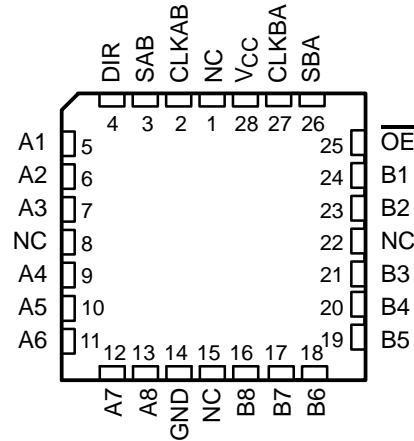
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 11$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths

SN54HC646 . . . JT OR W PACKAGE
SN74HC646 . . . DW OR NT PACKAGE
(TOP VIEW)



SN54HC646 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC646 devices consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'HC646 devices.

Output-enable (\overline{OE}) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{OE} is active (low). In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – NT	Tube	SN74HC646NT	HC646
	SOIC – DW	Tube	SN74HC646DW	
		Tape and reel	SN74HC646DWR	
-55°C to 125°C	CDIP – JT	Tube	SNJ54HC646JT	SNJ54HC646JT
	CFP – W	Tube	SNJ54HC646W	SNJ54HC646W
	LCCC – FK	Tube	SNJ54HC646FK	SNJ54HC646FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
INSTRUMENTS**

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SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

When an output function is disabled, the input function is still enabled and can be used to store data. Only one of the two buses, A or B, may be driven at a time.

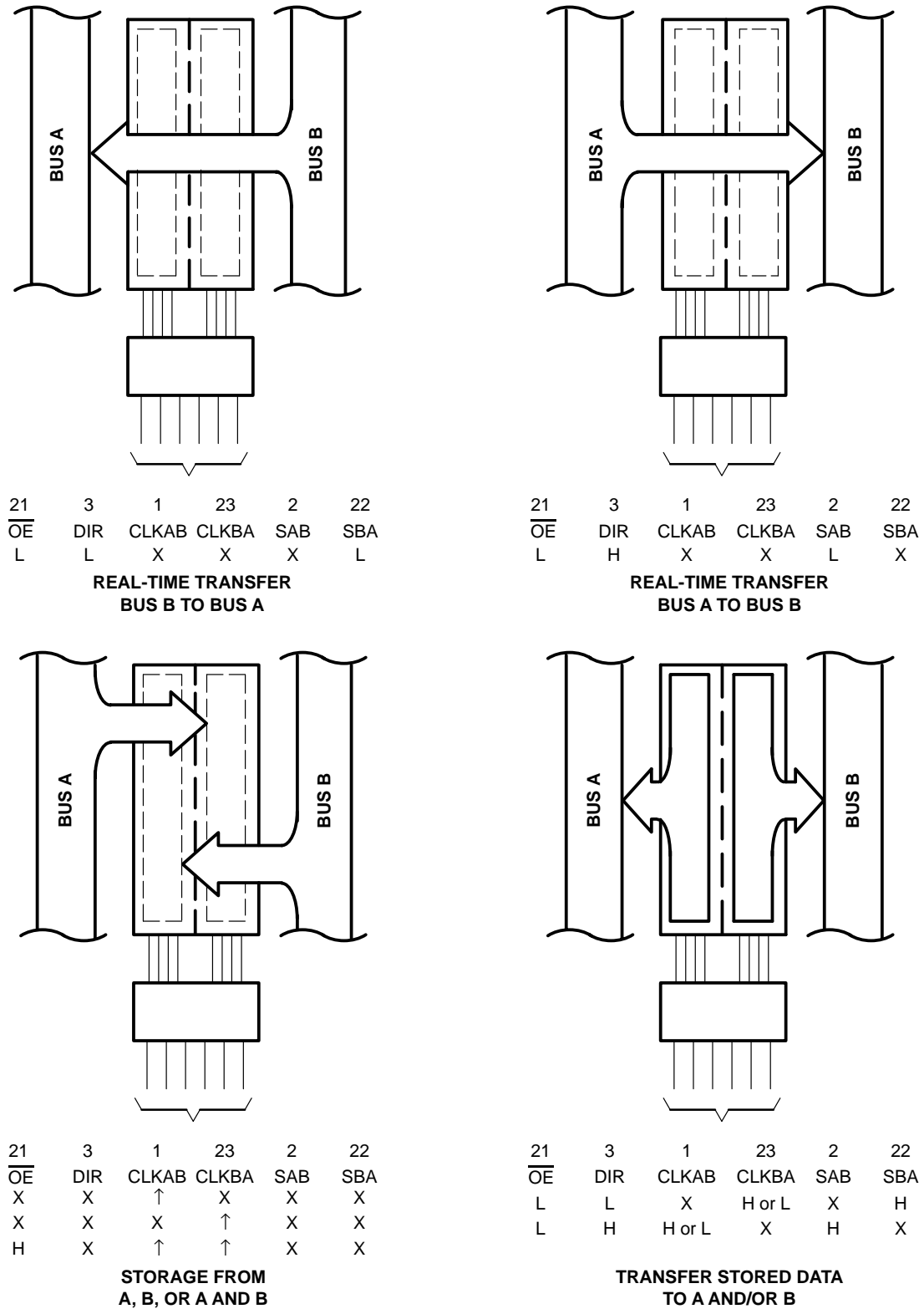
FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
X	X	↑	X	X	X	Input	Unspecified†	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified†	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to B bus

† The data-output functions can be enabled or disabled by various signals at \overline{OE} and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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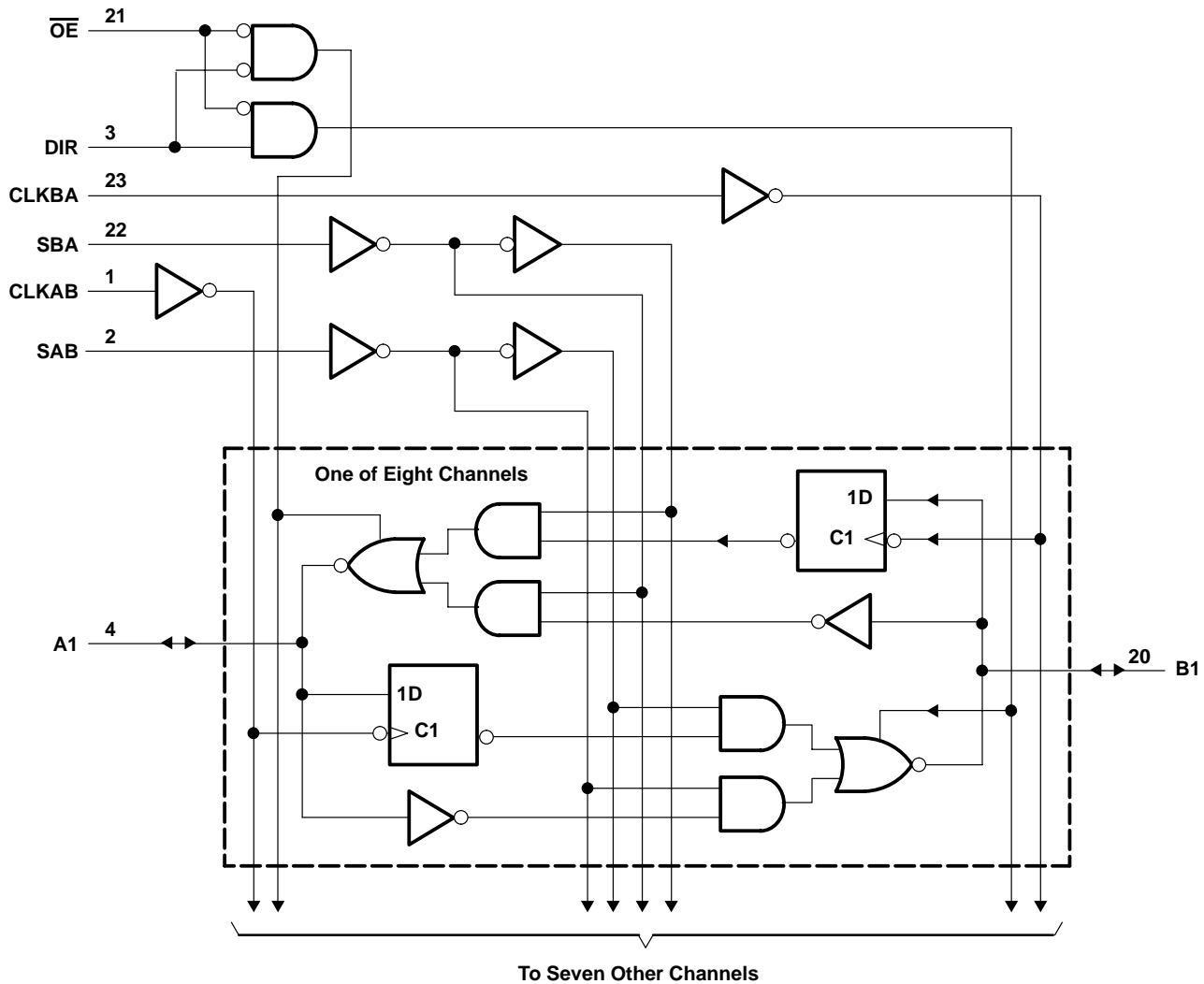
Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions

SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 35 mA
Continuous current through V_{CC} or GND	± 70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-3.



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SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 4)

		SN54HC646			SN74HC646			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V		1.5	1.5		V	
		V _{CC} = 4.5 V		3.15	3.15			
		V _{CC} = 6 V		4.2	4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5		0.5	V
		V _{CC} = 4.5 V			1.35		1.35	
		V _{CC} = 6 V			1.8		1.8	
V _I	Input voltage	0		V _{CC}	0		V _{CC}	V
V _O	Output voltage	0		V _{CC}	0		V _{CC}	V
t _t	Input transition (rise and fall) time	V _{CC} = 2 V			1000		1000	ns
		V _{CC} = 4.5 V			500		500	
		V _{CC} = 6 V			400		400	
T _A	Operating free-air temperature	-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC646		SN74HC646		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
I _I	Control inputs	V _I = V _{CC} or 0	6 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	A or B	V _O = V _{CC} or 0	6 V		±0.01	±0.5		±10		±5	μA
I _{CC}		V _I = V _{CC} or 0, I _O = 0	6 V			8		160		80	μA
C _i	Control inputs		2 V to 6 V		3	10		10		10	pF

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	V _{CC}	T _A = 25°C		SN54HC646		SN74HC646		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock} Clock frequency	2 V		6		4.3		5.5	MHz
	4.5 V		31		22		27	
	6 V		36		25		31	
t _w Pulse duration, CLKBA or CLKAB high or low	2 V		80		115		95	ns
	4.5 V		16		23		19	
	6 V		14		20		16	
t _{su} Setup time, A before CLKAB↑ or B before CLKBA↑	2 V		100		150		125	ns
	4.5 V		20		30		25	
	6 V		17		26		21	
t _h Hold time, A after CLKAB↑ or B after CLKBA↑	2 V		5		5		5	ns
	4.5 V		5		5		5	
	6 V		5		5		5	

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC646		SN74HC646		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	6	11		4.4		5.5	MHz	
			4.5 V	31	54		22		27		
			6 V	36	64		25		31		
t _{pd}	CLKBA or CLKAB	A or B	2 V		65	180		270		225	ns
			4.5 V		18	36		54		45	
			6 V		14	31		46		38	
	A or B	B or A	2 V		50	135		205		170	
			4.5 V		14	27		41		34	
			6 V		11	23		35		29	
	SBA or SAB†	A or B	2 V		70	190		285		240	
			4.5 V		20	38		57		48	
			6 V		16	32		48		41	
t _{en}	\overline{OE}	A or B	2 V		85	245		370		305	ns
			4.5 V		25	49		74		61	
			6 V		20	42		63		52	
t _{dis}	\overline{OE}	A or B	2 V		85	245		370		305	ns
			4.5 V		25	49		74		61	
			6 V		20	42		63		52	
t _{en}	DIR	A or B	2 V		80	245		370		305	ns
			4.5 V		25	49		74		61	
			6 V		20	42		63		52	
t _{dis}	DIR	A or B	2 V		80	245		370		305	ns
			4.5 V		25	49		74		61	
			6 V		20	42		63		52	
t _t		Any	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$
(unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC646		SN74HC646		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	CLKBA or CLKAB	A or B	2 V		90	265		400		330	ns
			4.5 V		24	53		80		66	
			6 V		20	46		68		57	
	A or B	B or A	2 V		70	220		335		280	
			4.5 V		20	44		67		56	
			6 V		15	38		57		49	
	SBA or SAB†	A or B	2 V		80	275		415		345	
			4.5 V		24	55		83		69	
			6 V		20	47		70		60	
t_{en}	\overline{OE}	A or B	2 V		113	330		500		410	ns
			4.5 V		33	66		100		82	
			6 V		27	57		85		71	
	DIR	A or B	2 V		113	330		500		410	
			4.5 V		33	66		100		82	
			6 V		27	57		85		71	
t_t		Any	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		43	

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	50	pF

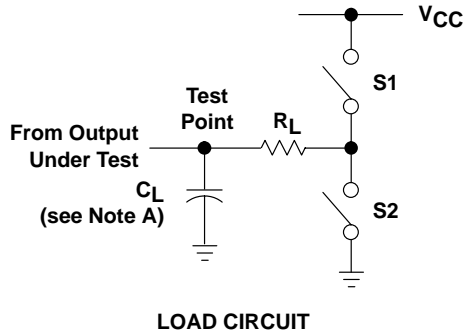
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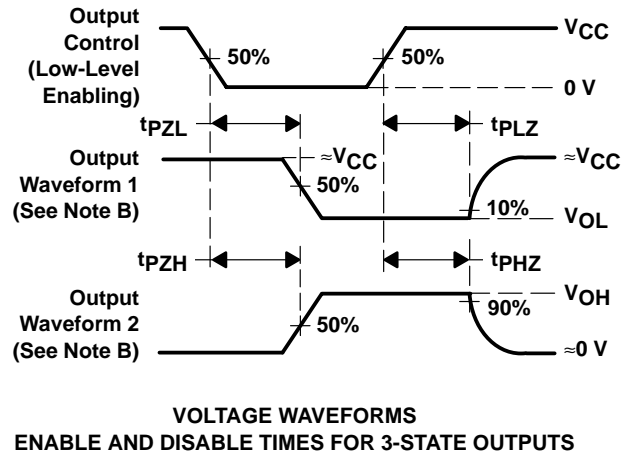
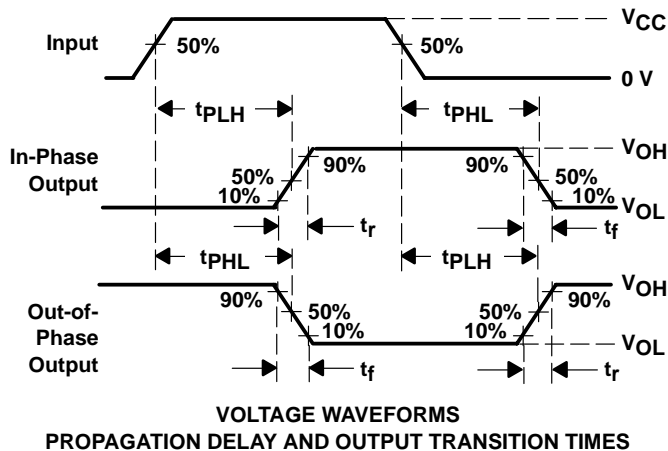
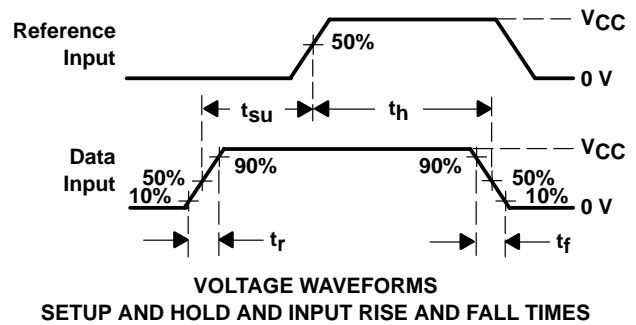
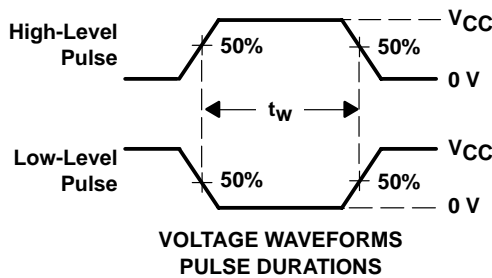
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PARAMETER MEASUREMENT INFORMATION



PARAMETER	R_L	C_L	S1	S2
t_{en}	1 k Ω	50 pF or 150 pF	Open	Closed
			Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
			Closed	Open
t_{pd} or t_t	—	50 pF or 150 pF	Open	Open



- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC646DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646	Samples
SN74HC646DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646	Samples
SN74HC646DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC646DWR	SOIC	DW	24	2000	367.0	367.0	45.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

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